a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals; and

a head slider provided with a head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

8. (Amended) A disk unit for reading information from and writing information to a disk, comprising:

a head assembly having a mounting surface, a head slider provided with a head, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the disk via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

Please add the following new claims 30-33:

30. (New) The head assembly as claimed in claim 1, wherein said layer covers at least an entire upper surface of the integrated circuit chip.

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31. (New) The head assembly as claimed in claim 1, wherein said layer covers upper and side surfaces of the integrated circuit chip.

32. (New) The head assembly as claimed in claim 1, further comprising:

an under-filling filling a gap between a lower surface of the integrated circuit chip and the mounting surface,

said layer covering upper and side surfaces of the integrated circuit chip and peripheral side surfaces of the under-filling.

33. (New) A unit for reading information from and writing information to a recording medium, comprising:

a head assembly having a mounting surface, a head slider provided with a head, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the recording medium via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.